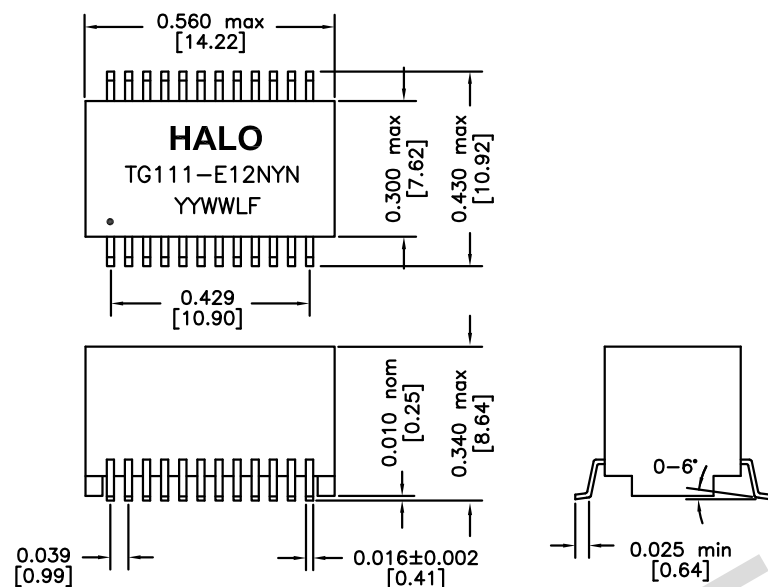
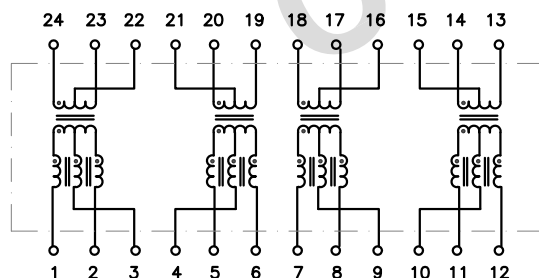




DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ± 0.005 INCH IF NOT SPECIFIED



PART NO. : TG111-E12NYNLF

24PIN 0.039" LEAD PITCH SMT PACKAGE

DESIGNED FOR ONE-PORT GIGABIT, IEEE802.3ab OR
DUAL-PORT FAST ETHERNET, IEEE802.3u APPLICATIONS

COMPLIANT WITH IEEE802.3af REQUIREMENTS WITH
350mA CURRENT CARRYING CAPACITY FOR PoE

AUTO-MDIX COMPATIBLE

LEAD-FREE/ROHS COMPLIANT, "GREEN PRODUCT"

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

EXTENDED OPERATING TEMPERATURE $-40/+85^{\circ}\text{C}$

ELECTRICAL SPECIFICATIONS @ 25°C

Turns Ratio	1CT:1CT $\pm 2\%$
OCL (100KHz, 0.1Vrms, 8mADC)	350 μH min
Insertion Loss 1-100MHz	-1.1dB max
Return Loss 1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CMR 1-100MHz	-40dB typ
Crosstalk 1-30MHz	-50dB typ
60MHz	-45dB typ
100MHz	-40dB typ
Isolation	1,500Vrms

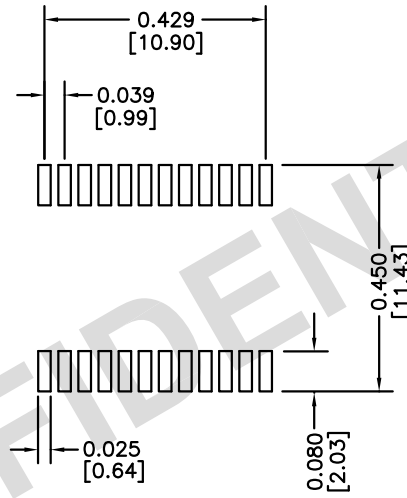


HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE
FOR	FAST/GIGABIT ETHERNET
PART NO.	TG111-E12NYNLF
SCALE	NONE
PAGE	1 OF 2

SIGNATURES	DATE	REV.	DESC.	DATE
DRAWN LI ZHI ZHONG	4/29/11	A	FIRST ISSUE	4/29/11
CHECKED LEI KEONG	5/17/11	B	PROD. RELEASE	5/17/11
APPROVED PETER LU	5/17/11			
FILE E12NYNLF.DWG				



RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE	SIGNATURES	DATE	REV.	DESC.	DATE
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PAGE	2 OF 2	FILE E12NYNLF.DWG				